



SMAF

Material Content Declaration					
Material name	Substance name, e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 35.24%	Copper (Cu)	7440-50-8	8.424	99.81	351,732.8
	Phosphorus (P)	7723-14-0	0.003	0.04	125.3
	Iron (Fe)	7439-89-6	0.013	0.15	542.8
	Total		8.44		
Solder Paste 1.34%	Lead (Pb)	7439-92-1	0.296	92.5	12,359.1
	Tin (Sn)	7440-31-5	0.016	5.0	668.1
	Silver (Ag)	7440-22-4	0.008	2.5	334.0
	Total		0.32		
Chip 3.09%	Silicon (Si)	7440-21-3	0.706	95.4	29,478.1
	Lead (Pb)	7439-92-1	0.034	4.6	1,419.6
	Total		0.74		
Molding 59.79%	Silica	60676-86-0	11.098	77.5	463,382.0
	Epoxy resin	29690-82-2	1.432	10	59,791.2
	Phenolic resin	9003-35-4	1.146	8.0	47,849.7
	Fire Retardant	Trade secret	0.573	4.0	23,924.8
	Carbon Black	1333-86-4	0.071	0.5	2,964.5
	Total		14.32		
Plating 0.54%	Tin (Sn)	7440-31-5	0.130	100.00	5,428.0
	Total		0.13		
	(mg)		23.95		